Chapter 2: Memory Hierarchy Design (Part 3)

Introduction

Caches

Main Memory (Section 2.2)

Virtual Memory (Section 2.4, Appendix B.4, B.5)

Memory Technologies

Dynamic Random Access Memory (DRAM)

Optimized for density, not speed

One transistor cells

Multiplexed address pins

Row Address Strobe (RAS)

Column Address Strobe (CAS)

Cycle time > access time

Destructive reads

Must refresh every few ms

Access every row

Sold as dual inline memory modules (DIMMs)

1 2

Memory Technologies, cont.

Static Random Access Memory (SRAM)

Optimized for speed, then density

Typically 6 transistors per cell

Separate address pins

 $\mathsf{Static} \Rightarrow \mathsf{No}\; \mathsf{Refresh}$

Greater power dissipation than DRAM

Access time = cycle time

DRAM Organization

DIMM

Rank

Bank

Array

Row buffer

3

DRAM Organization

Rank: chips needed to respond to a single request

Assume 64 bit data bus

For 8 bit DRAM, need 8 chips in a rank

For 4 bit DRAM, need 16 chips in a rank

Can have multiple ranks per DIMM

Bank: A chip is divided into multiple independent banks for pipelined access

Array: A bank consists of many arrays, 1 array per bit of output, for parallel access

Row buffer: A "cache" that preserves the last row read from a bank

DRAM Organization

See figure 1.5 in

6

The Memory System: You Can't Avoid It, You Can't Ignore It, You Can't Fake It

By Bruce Jacob

Synthesis Lectures on Computer Architecture, Morgan & Claypool

Series editor: Mark Hill

Downloadable from U of I accounts

https://www.morganclaypool.com/doi/pdfplus/10.2200/S00201ED1V 01Y200907CAC007

5

Internals of a DRAM Array

See Figure 1.6 of the synthesis lecture

Steps to access a bit

Pre-charge bit lines

Activate row: turn on word line for the row, brings data to sense amps

Column read: send subset of data (columns)

(Restore data)

DRAM Optimizations - Page Mode

Unoptimized DRAM

First read entire row

Then select column from row

Stores entire row in a buffer

Page Mode

Row buffer acts like an SRAM

By changing column address, random bits can be accessed within a row.

7 8

DRAM Optimizations - Synchronous DRAM

Previously, DRAM had asynchronous interface

Each transfer involves handshaking with controller

Synchronous DRAM (SDRAM)

Clock added to interface

Register to hold number of bytes requested

Send multiple bytes per request

Double Data Rate (DDR)

Send data on rising and falling edge of clock

Simple Main Memory

Consider a memory with these parameters:

1 cycle to send address

6 cycles to access each word

1 cycle to send word back to CPU/Cache

What's the miss penalty for a 4word block?

 $(1 + 6 \text{ cycles} + 1 \text{ cycle}) \times 4 \text{ words}$ = 32 cycles

How can we speed this up?

9 10

Wider Main Memory

Make the memory wider

Read out 2 (or more) words in parallel

Memory parameters:

1 cycle to send address

6 cycles to access each doubleword

1 cycle to send doubleword back to CPU/Cache

Miss penalty for a 4 word block:

 $(1 + 6 \text{ cycles} + 1 \text{ cycle}) \times 2 \text{ doublewords}$

= 16 cycles

Cost

Wider bus

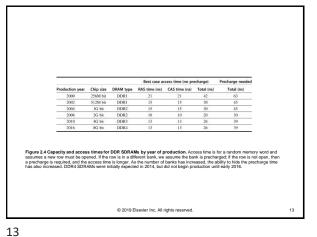
Larger expansion size

Organize memory in banks
Subsequent words map to different banks
Word A in bank (A mod M)
Within a bank, word A in location (A div M)

Word address

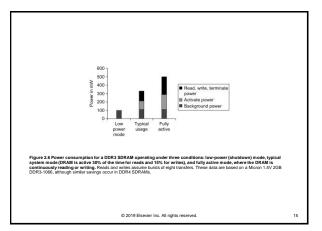
Bank
Word in Bank
How many banks to include?

11 12



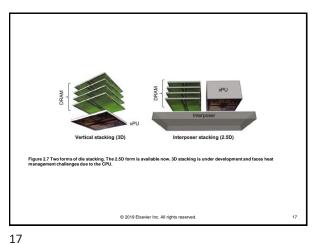
Standard	I/O clock rate	M transfers/s	DRAM name	MIB/s/DIMM	DIMM name	
DDRI	133	266	DDR266	2128	PC2100	
DDRI	150	300	DDR300	2400	PC2400	
DDRI	200	400	DDR400	3200	PC3200	
DDR2	266	533	DDR2-533	4264	PC4300	
DDR2	333	667	DDR2-667	5336	PC5300	
DDR2	400	800	DDR2-800	6400	PC6400	
DDR3	533	1066	DDR3-1066	8528	PC8500	
DDR3	666	1333	DDR3-1333	10,664	PC10700	
DDR3	800	1600	DDR3-1600	12,800	PC12800	
DDR4	1333	2666	DDR4-2666	21,300	PC21300	
re 2.5 Clock rates, banns. The third column is lifth column is eight time ficant first use in 2016.	lwidth, and names	of DDR DRAMS	and DIMMs in s the number fro	2016. Note the r	numerical relations	the DRAM chip.

14



Other Technologies Graphics Data RAMS (GDDR) Wider (32 bits), higher clock, connect directly to GPUs (soldered to board vs. DIMMs) Die stacked DRAMs / 3D / High Bandwidth Memory (HBM) Nonvolatile memory (later) Flash Phase change Reliability: Parity, ECC, chipkill

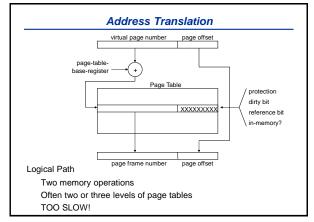
15 16



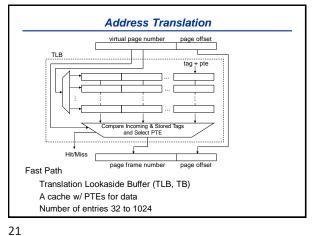
Virtual Memory User operates in a virtual address space, mapping between virtual space and main memory is determined at runtime Original Motivation Avoid overlays Use main memory as a cache for disk Current motivation Relocation Protection Sharing Fast startup Engineered differently than CPU caches Miss access time O(1,000,000) Miss access time >> miss transfer time

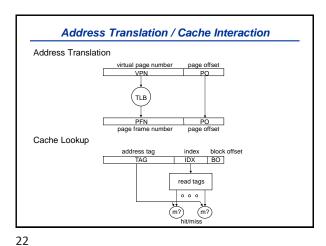
18

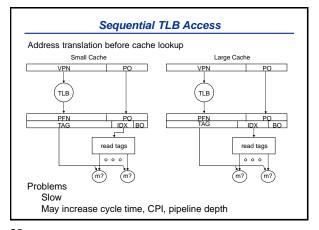
Virtual Memory, cont. Blocks, called pages, are 512 to 16K bytes. Page placement Fully-associative -- avoid expensive misses Page identification Address translation -- virtual to physical address Indirection through one or two page tables Translation cached in translation buffer Page replacement Approx. LRU Write strategy Writeback (with page dirty bit)

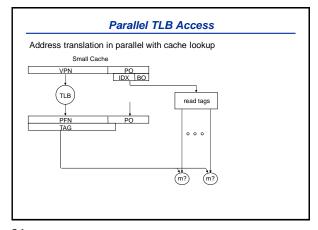


19 20

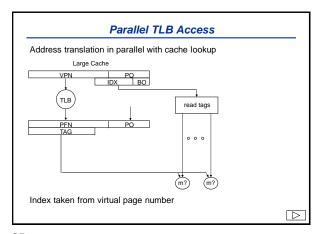


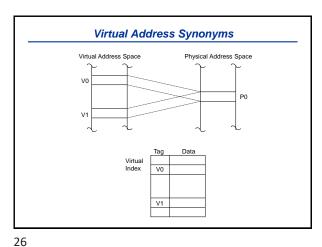




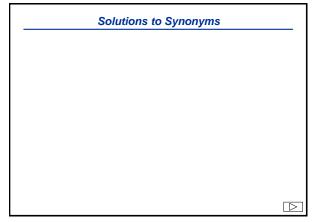


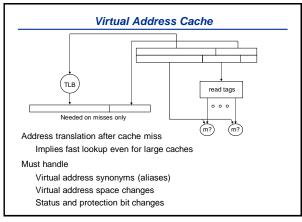
23 24





25 2





27 28

Protection

Goal:

One process should not be able to interfere with the execution of another

Process model

Privileged kernel

Independent user processes

Primitives vs. Policy

Architecture provides the primitives

Operating system implements the policy

Problems arise when hardware implements policy

Protection Primitives

User vs. Kernel

30

At least one privileged mode

Usually implemented as mode bit(s)

How do we switch to kernel mode?

Change mode and continue execution at predetermined location

Hardware to compare mode bits to access rights

Access certain resources only in kernel mode

29

Protection Primitives, cont.

Base and Bounds

Privileged registers
Base ≤ Address ≤ Bounds

Pagelevel protection

Protection bits in page table entry

Cache them in TLB

31